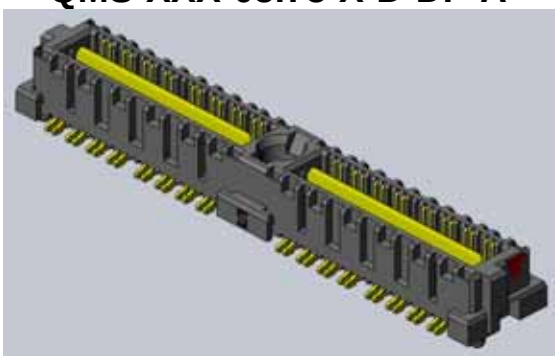
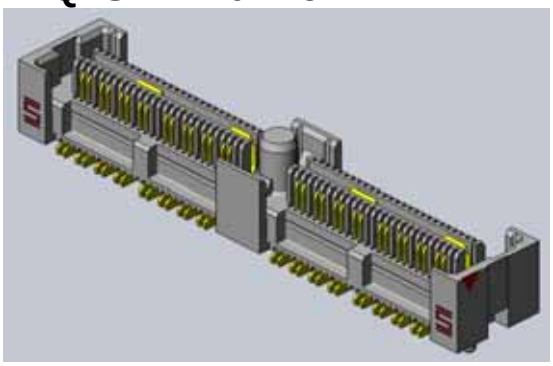
High Speed Characterization Report

QMS-XXX-05.75-X-D-DP-A



Mates with

QFS-XXX-04.25-X-D-DP-A



Description:
Micro High Speed Board-to-Board, 0.635mm Pitch, 10mm (0.3935") Stack Height

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Report Revision: 7/13/2012

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Connector Overview

Micro High Speed 0.635mm (0.0250") pitch interfaces (QFS-DP/QMS-DP Series) are capable of XAUI, PCI Express and SATA data rates. The QFS-DP/QMS-DP Series are available with up to 64 contacts per row. QFS/QMS series board-to-board spacing is available in a 10mm (0.3935”), 11mm (0.4330"), 12mm (0.4724"), 13mm (0.5118"), 14mm (0.5512") and 16mm (0.630") stack height. The data in this report is applicable only to the 10mm (0.3935”) board-to-board mated connector stack height.

Connector System Speed Rating

QFS-DP/QMS-DP Series, Parallel Board-to-Board, 0.635mm (0.0250”) Pitch, 10mm Stack Height

Signaling	Speed Rating
Differential:	**9GHz/ 18Gbps**

The Speed Rating is based on the -3 dB insertion loss point of the connector system. The -3 dB point can be used to estimate usable system bandwidth in a typical, two-level signaling environment.

To calculate the Speed Rating, the measured -3 dB point is rounded-up to the nearest half-GHz level. The up rounding corrects for a portion of the test board’s trace loss, since a short length of trace loss included in the loss data in this report. The resulting loss value is then doubled to determine the approximate maximum data rate in Gigabits per second (Gbps).

For example, a connector with a -3 dB point of 7.8 GHz would have a Speed Rating of 8 GHz/ 16 Gbps. A connector with a -3 dB point of 7.2 GHz would have a Speed Rating of 7.5 GHz/ 15 Gbps.

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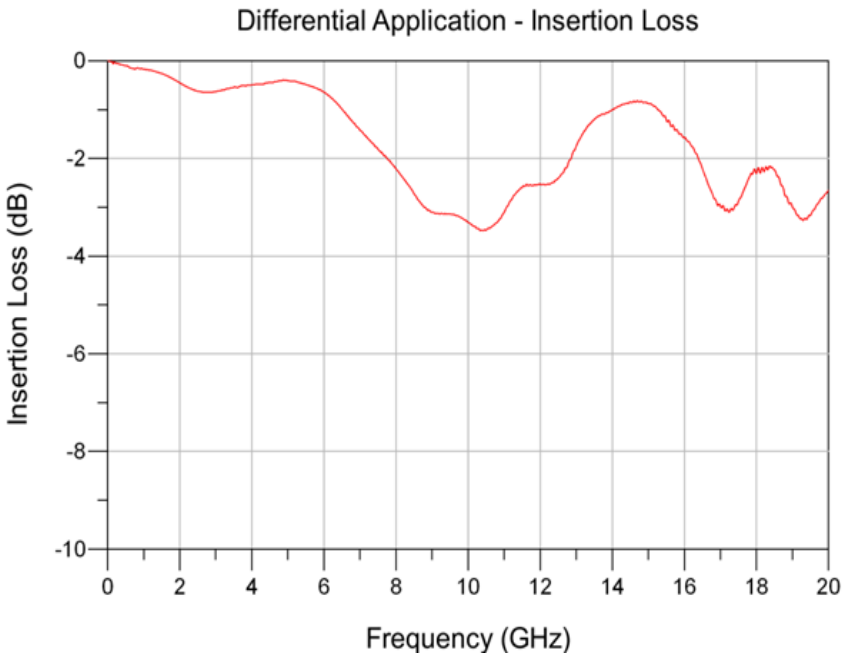
Frequency Domain Data Summary

Table 1 - Differential Connector System Performance		
Test Parameter	**Configuration**	
Insertion Loss	SS	3dB@ 8.79 GHz
Return Loss	SS	>10dB to 6.38 GHz
Near-End Crosstalk	AAQQ	<-20dB to 20.0 GHz
	Xrow, AA to QQ	<-20dB to 20.0 GHz
Far-End Crosstalk	AAQQ	<-20dB to 20.0 GHz
	Xrow, AA to QQ	<-20dB to 20.0 GHz

Bandwidth Chart – Differential Insertion Loss

QFS-DP/QMS-DP Connector Series



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Time Domain Data Summary

Table 2 - Differential Impedance (Ω)					
Signal Rise-time	**30ps**	**50ps**	**100ps**	**250ps**	**500ps**
Maximum Impedance	107.7	106.3	104.3	100.9	100.4
Minimum Impedance	64.8	70.9	79.6	85.6	92.2

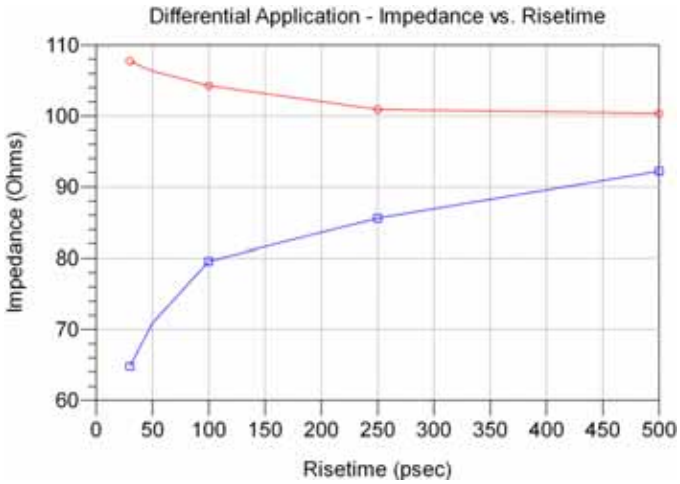

Table 3 - Differential Crosstalk (%)						
Input(t_r)		**30ps**	**50ps**	**100ps**	**250ps**	**500ps**
NEXT	AAQQ	2.3	2.0	1.8	1.0	0.55
	Xrow	<0.1	<0.1	<0.1	<0.1	<0.1
FEXT	AAQQ	0.93	0.74	0.52	0.26	0.12
	Xrow	<0.1	<0.1	<0.1	<0.1	<0.1

Table 4 - Propagation Delay (Mated Connector)	
Differential	75ps

Series: QFS-DP/QMS-DP
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Characterization Details

This report presents data that characterizes the signal integrity response of a connector pair in a controlled printed circuit board (PCB) environment. All efforts are made to reveal typical best-case responses inherent to the system under test (SUT).

In this report, the SUT includes the connector pair and footprint effects on a typical multi-layer PCB. PCB effects (trace loss) are de-embedded from test data. Board related effects, such as pad-to-ground capacitance, are included in the data presented in this report.

Additionally, intermediate test signal connections can mask the connector's true performance. Such connection effects are minimized by using high performance test cables and adapters. Where appropriate, calibration and de-embedding routines are also used to reduce residual effects.

Differential Data

Most Samtec connectors can be used successfully in both differential and single-ended applications. However, electrical performance will differ depending on the signal drive type. In this report, data is presented for a differentially driven only scenario where every third pin of the standard Samtec connector is removed.

Connector Signal to Ground Ratio

Samtec connectors are most often designed for generic applications and can be implemented using various signal and ground pin assignments. In high-speed systems, provisions must be made in the interconnect for signal return currents. Such paths are often referred to as "ground". In some connectors, a ground plane or blade, or an outer shield, is used as the signal return, while in others, connector pins are used as signal returns. Various combinations of signal pins, ground blades, and shields can also be utilized. Electrical performance can vary significantly depending upon the number and location of ground pins.

In general, the more pins dedicated to ground, the better electrical performance will be. However, dedicating pins to ground reduces signal density of a connector. Therefore, care must be taken when choosing signal/ground ratios in cost or density-sensitive applications.

Series: QFS-DP/QMS-DP
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For this connector, the following configurations are evaluated:

Differential Impedance**:**
- SS (positive signal-negative signal)

Differential Crosstalk**:**
- Electrical “worst case”: AAQQ (active-active-quiet-quiet)
- Across row: “xrow case”: AA to QQ (from one row of terminals to the other row across the ground blade, same spacing within the row)

In all cases in this report, the center ground blade of the connector was grounded to the PCB. Only one differential pair was driven for crosstalk measurements.

Other configurations can be evaluated upon request. Please contact sig@samtec.com for more information.

In a real system environment, active signals might be located at the outer edges of the signal contacts of concern, as opposed to the ground signals utilized in laboratory testing. For example, in a single-ended system, a pin-out of “SSSS”, or four adjacent single ended signals might be encountered as opposed to the “GSG” and “GSSG” configurations tested in the laboratory. Electrical characteristics in such applications could vary slightly from laboratory results. However, in most applications, performance can safely be considered equivalent.

Signal Edge Speed (Rise Time):
In pulse signaling applications, the perceived performance of an interconnect can vary significantly depending on the edge rate or rise time of the exciting signal. For this report, the fastest rise time used was 30 ps. Generally, this should demonstrate worst-case performance.

In many systems, the signal edge rate will be significantly slower at the connector than at the driver launch point. To estimate interconnect performance at other edge rates, data is provided for several rise times between 30ps and 500ps.

For this report, measured rise times were at 10%-90% signal levels.

Frequency Domain Data
Frequency Domain parameters are helpful in evaluating the connector system’s signal loss and crosstalk characteristics across a range of sinusoidal frequencies. In this report, parameters presented in the Frequency Domain are Insertion Loss, Return Loss, and Near-End and Far-End Crosstalk. Other parameters or formats, such as VSWR or S-Parameters, may be available upon request. Please contact our Signal Integrity Group at sig@samtec.com for more information.

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Frequency performance characteristics for the SUT are generated directly from network analyzer measurements.

Time Domain Data
Time Domain parameters indicate Impedance mismatch versus length, signal propagation time, and crosstalk in a pulsed signal environment. The measured S-Parameters from the network analyzer are post-processed using Agilent Advanced Design System to obtain the time domain response. Time Domain procedure is provided in Appendix E of this report. Parameters or formats not included in this report may be available upon request. Please contact our Signal Integrity Group at sig@samtec.com for more information.

In this report, propagation delay is defined as the signal propagation time through the connector and connector footprint. It includes 10 mils of PCB trace on the QMS-DP and QFS-DP connector side each. Delay is measured at 30 picoseconds signal rise time. Delay is calculated as the difference in time measured between the 50% amplitude levels of the input and output pulses.

Crosstalk or coupled noise data is provided for various signal configurations. All measurements are single disturber. Crosstalk is calculated as a ratio of the input line voltage to the coupled line voltage. The input line is sometimes described as the active or drive line. The coupled line is sometimes described as the quiet or victim line. Crosstalk ratio is tabulated in this report as a percentage. Measurements are made at both the near-end and far-end of the SUT.

Data for other configurations may be available. Please contact our Signal Integrity Group at sig@samtec.com for further information.

As a rule of thumb, 10% crosstalk levels are often used as a general first pass limit for determining acceptable interconnect performance. However, modern system crosstalk tolerance can vary greatly. For advice on connector suitability for specific applications, please contact our Signal Integrity Group at sig@samtec.com.

Additional information concerning test conditions and procedures is located in the appendices of this report. Further information may be obtained by contacting our Signal Integrity Group at sig@samtec.com.

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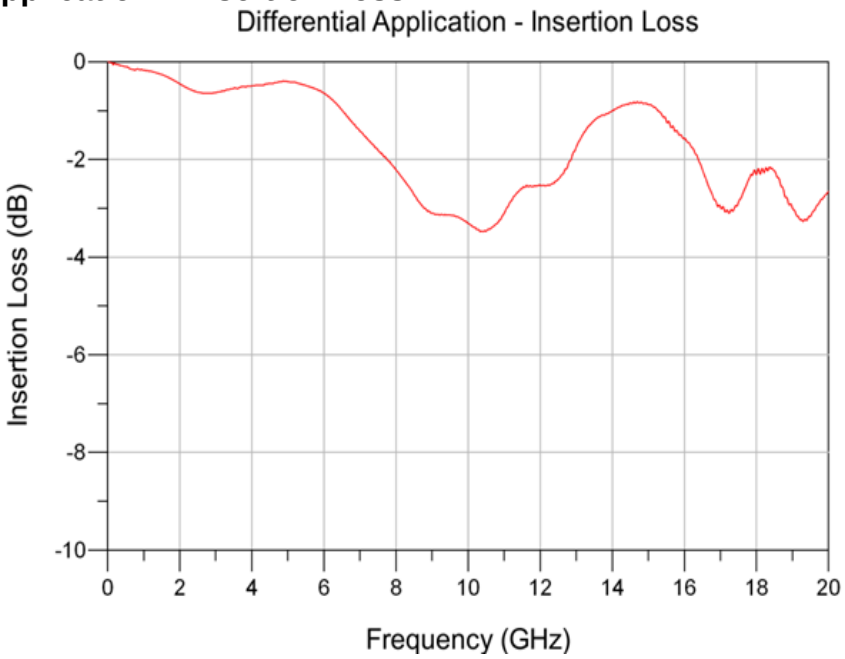
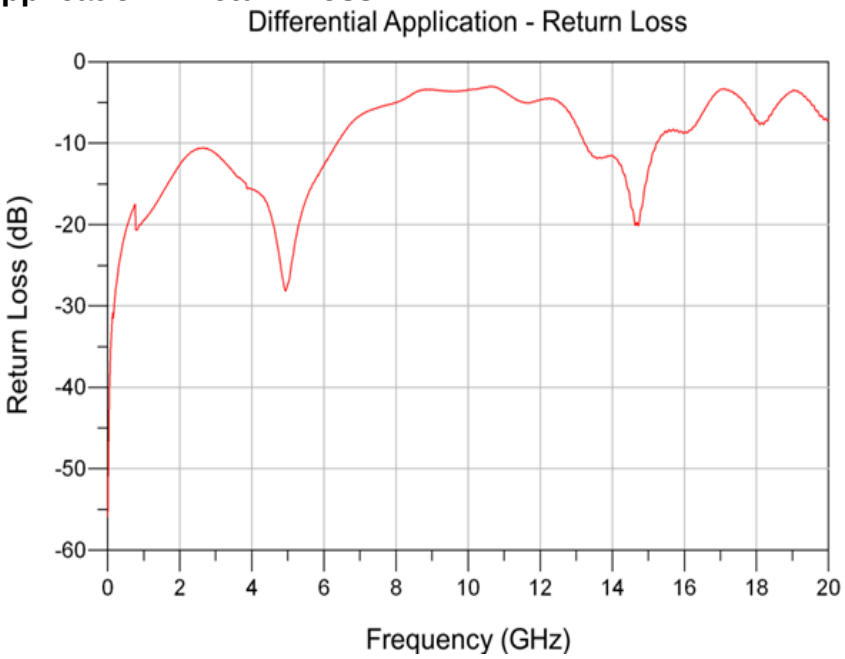
Appendix A – Frequency Domain Response Graphs

Differential Application – Insertion Loss



Differential Application – Return Loss



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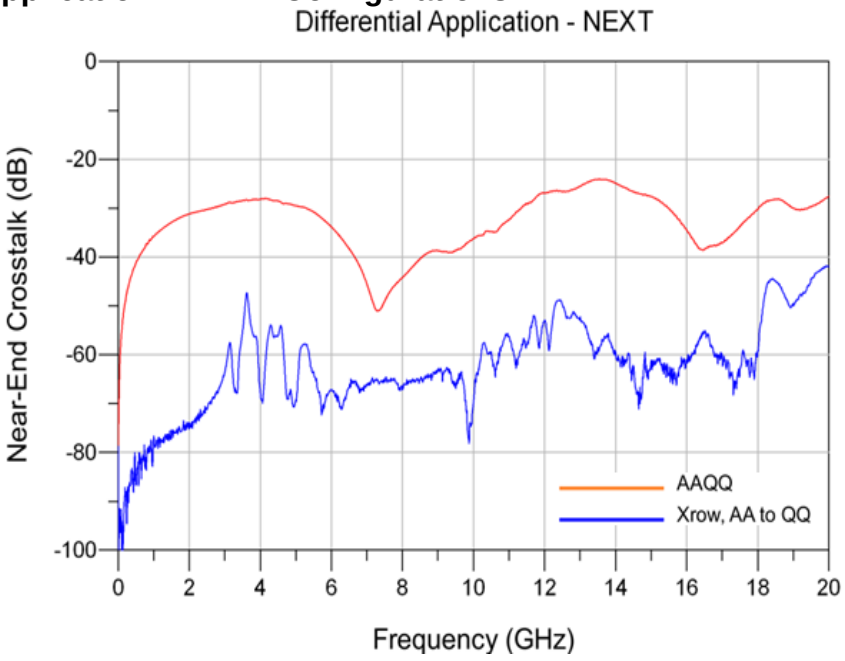
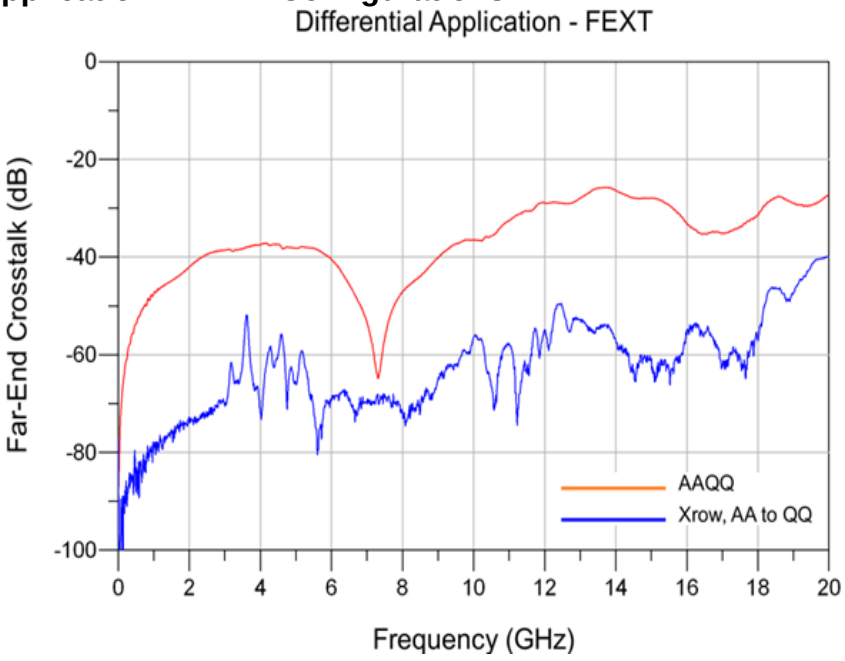
Differential Application – NEXT Configurations



Differential Application – FEXT Configurations



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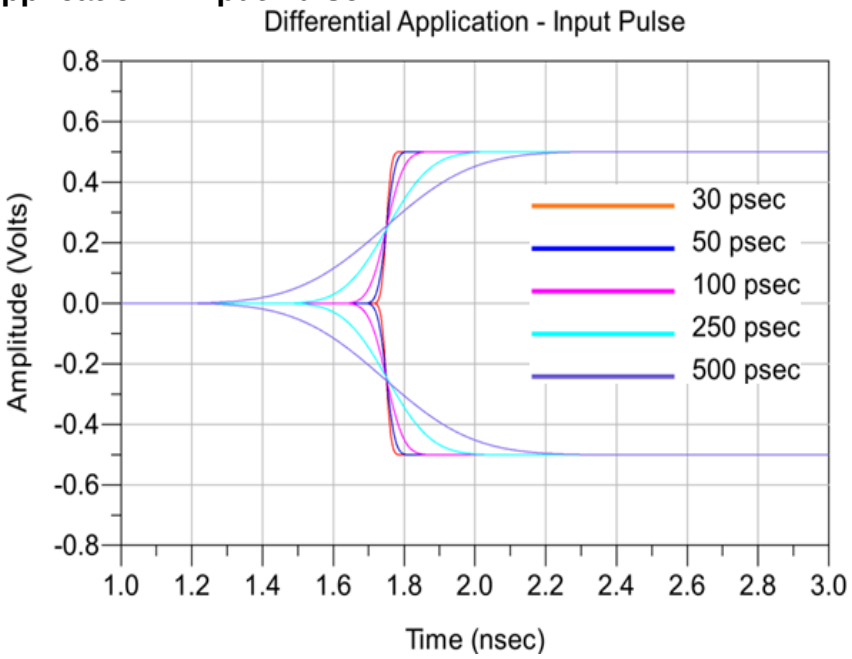
Appendix B – Time Domain Response Graphs

Differential Application – Input Pulse



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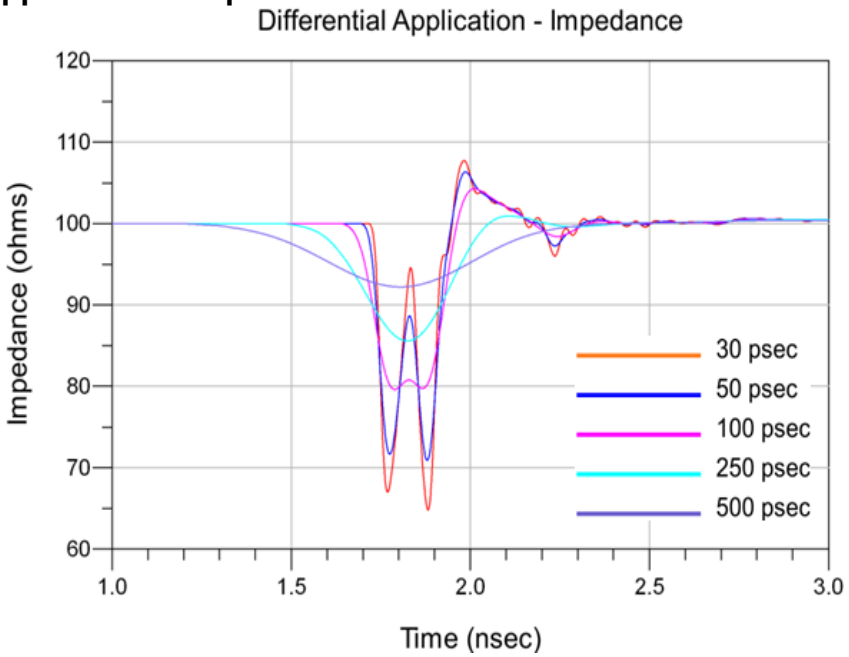
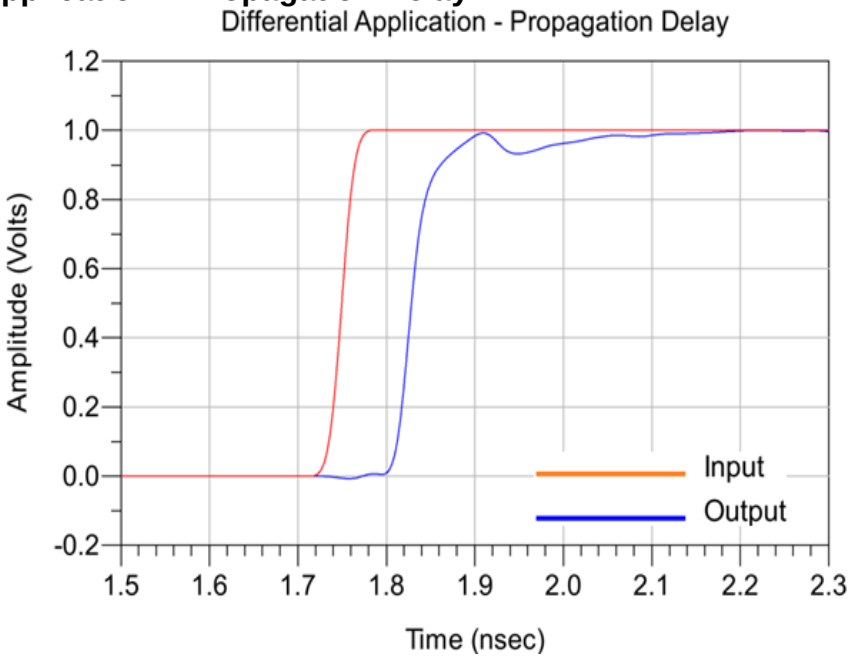
Differential Application – Impedance



Differential Application – Propagation Delay



Series: QFS-DP/QMS-DP
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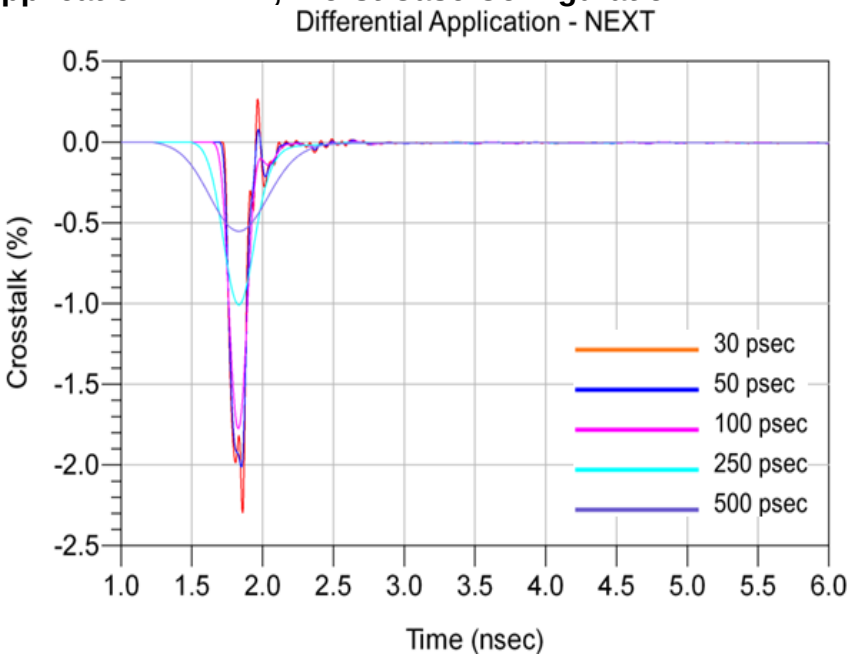
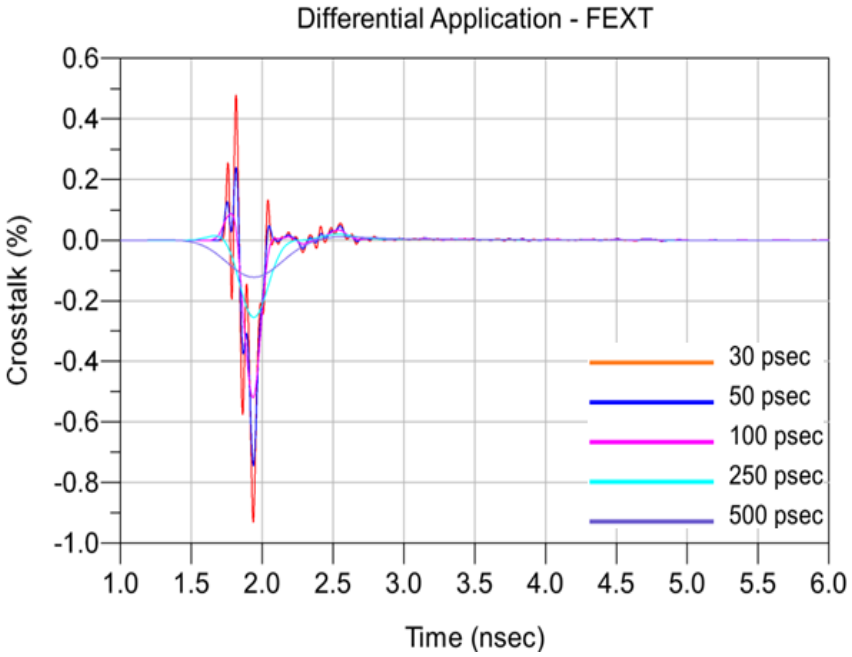
Differential Application – NEXT, Worst Case Configuration

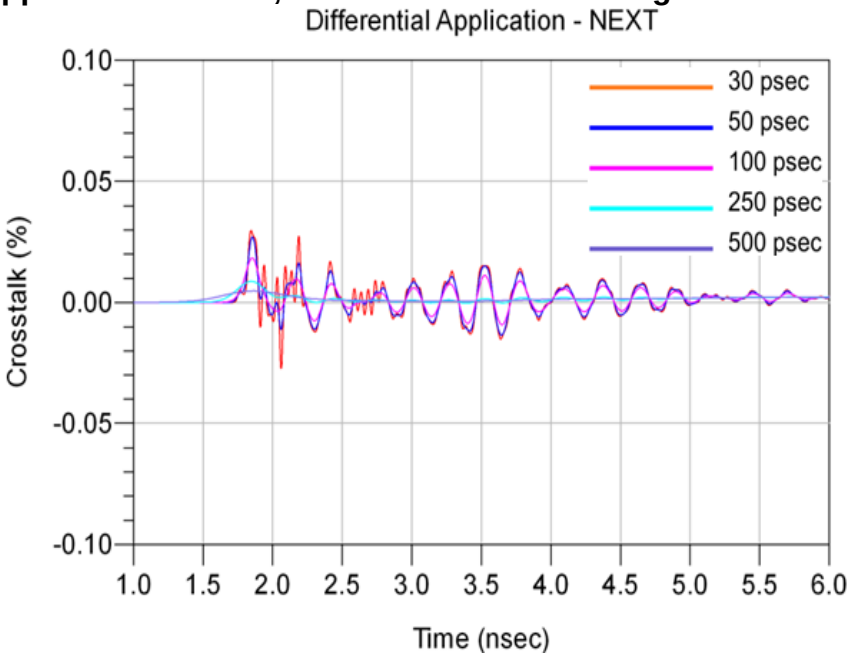


Differential Application – FEXT, Worst Case Configuration

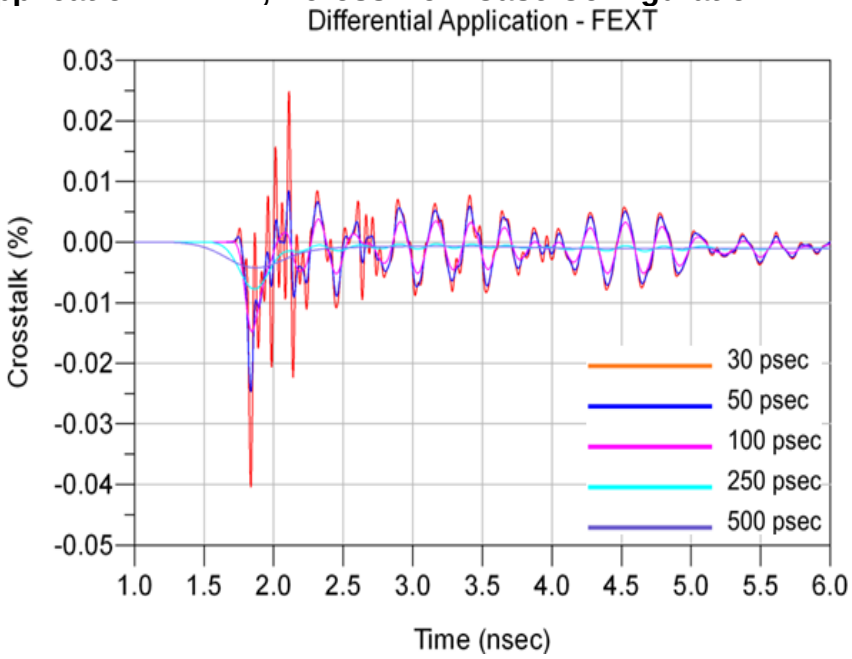


Series: QFS-DP/QMS-DP
Description: Micro High Speed Board-to-Board, 0.635mm Pitch, 10mm (0.3935") Stack Height

Differential Application – NEXT, Across Row Case Configuration



Differential Application – FEXT, Across Row Case Configuration



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Appendix C – Product and Test System Descriptions

Product Description

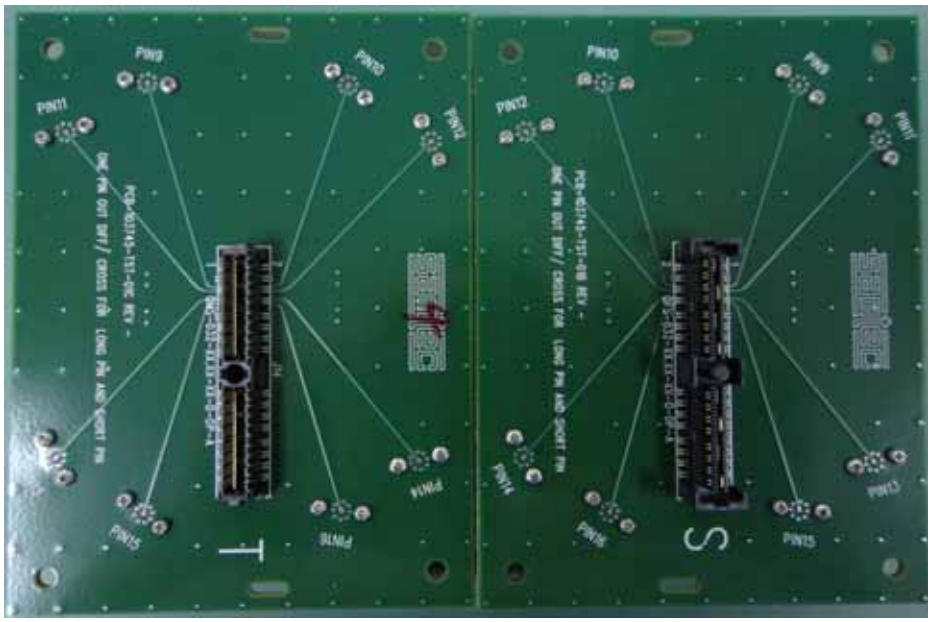
Product test samples are 10mm (0.3935'') stack height QFS-DP/ QMS-DP Series connectors. The part numbers are QFS-032-04.25-H-D-DP-A and QMS-032-05.75-L-D-DP-A. The QFS/ QMS Series connector are surface mount products. Each connector has two rows of contacts evenly spaced on a 0.635mm (0.025") pitch. A ground/power blade lies lengthwise between terminal rows in the housing. The QFS/ QMS Series connectors use a strip contact system. A photo of the test articles mounted to SI test boards is shown below.

Test System Description

The test fixtures are composed of four-layer FR-4 material with 50Ω signal trace and pad configurations designed for the electrical characterization of Samtec high speed connector products. A PCB mount SMA connector is used to interface the VNA test cables to the test fixtures. Optimization of the SMA launch was performed using full wave simulation tools to minimize reflections. Two test fixtures are specific to the QFS-DP/ QMS-DP Series connector set and identified by part numbers PCB-103745-TST-01B and PCB-103745-TST-01C. Calibration standards specific to the QFS-DP/ QMS-DP Series are located on the calibration boards PCB-103745-TST-03 or PCB-103745-TST-04. To keep trace lengths short, three different test board sets were required to access the necessary signal pins.

PCB-103745-TST-XX Test Fixtures

Shown below is a photograph of the test board set.



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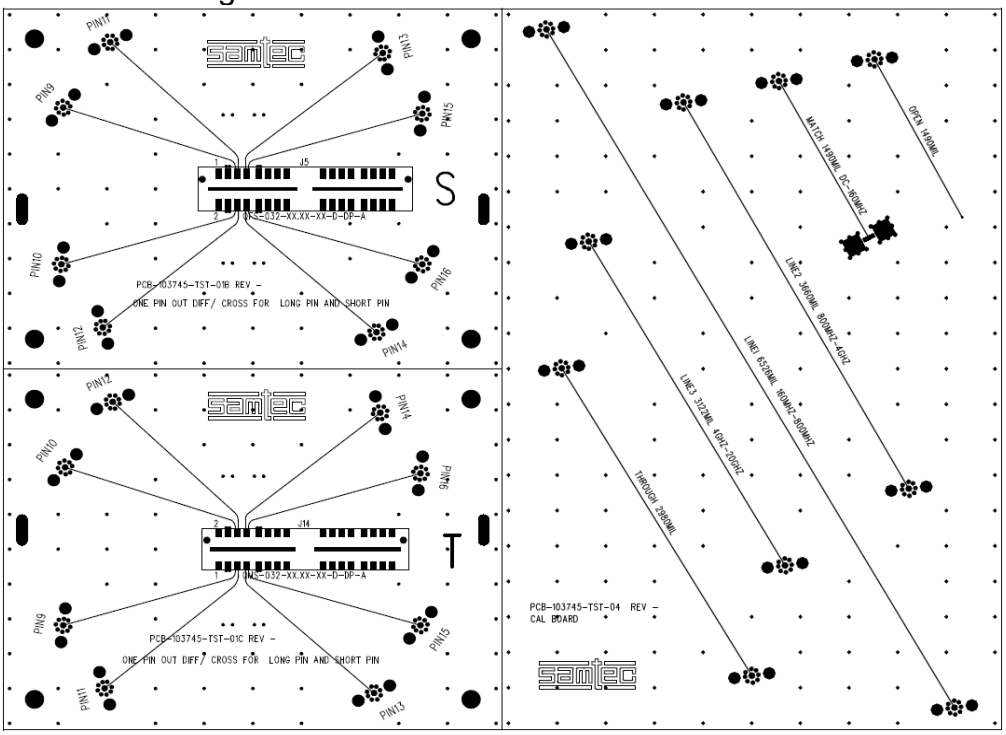
PCB-103745-TST-XX PCB Layout Panel

Artwork of the PCB design is shown below.



PCB Fixtures

The test fixtures used are as follows:

PCB-103745-TST-01B Rev – QFS-DP Series Test Board for worst-case and cross row crosstalk

PCB-103745-TST-01C Rev – QMS-DP Series Test Board for worst-case and cross row crosstalk

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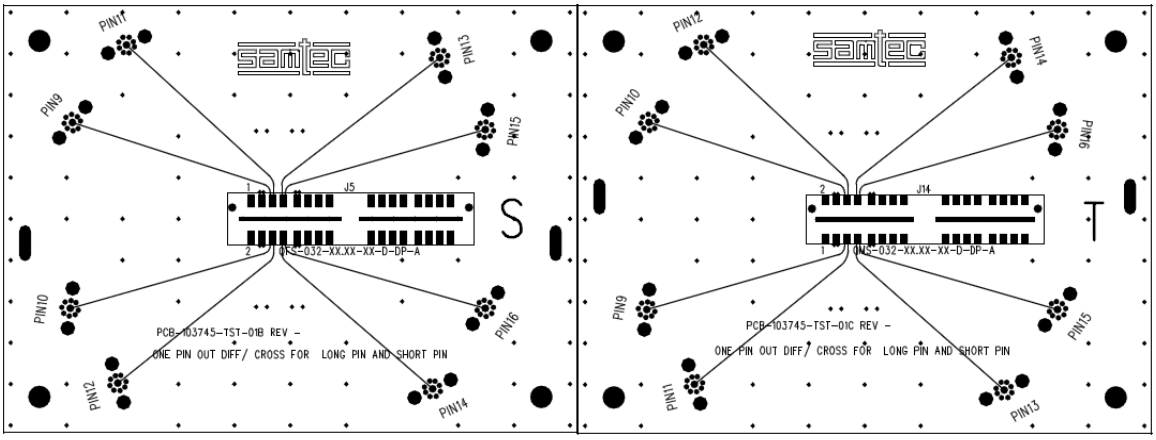

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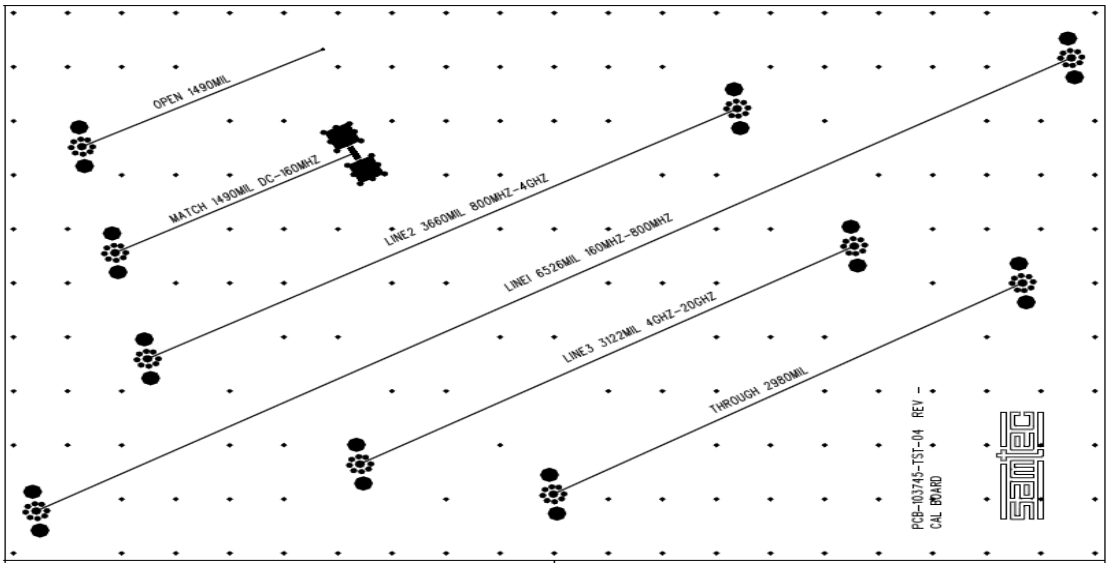
Calibration Board

Test fixture losses and test point reflections were removed from the data by use of TRL calibration. The calibration board is shown below. Prior to making any measurements, the calibration board is characterized to obtain parameters required to define the calibration kit. Once a calibration kit is defined, calibration using the standards on the calibration board can be performed. Finally, the device can be measured and the test board effects are automatically removed.



Thru line – 2980 mils
Open Reflect – 1490 mils
Line 1 – 6526 mils
Line 2 – 3660 mils
Line 3 – 3122 mils
Match – 1490 mils

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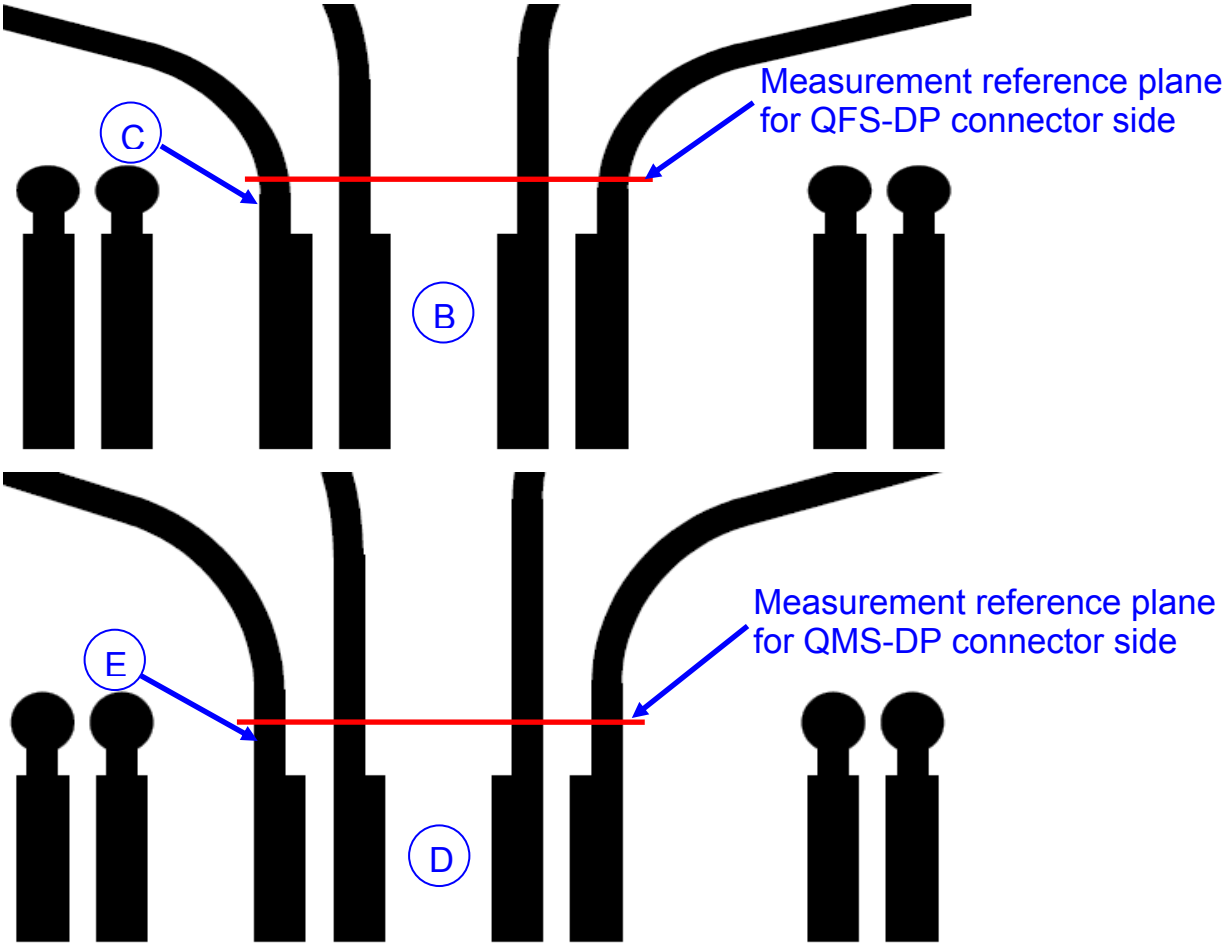
All traces on the test boards are length matched to 1.5” measured from the edge of the pad to the SMA. The TRL calibration effectively removes 1.49” of test board trace effects. This means that 10 mils of test board trace length effects are included in the both sides of test boards in the measurement. The S-Parameter measurement includes:

A- The QFS-DP/QMS-DP Series connector set
B- Test board vias, pads (footprint effects) for the QFS-DP connector side.
C- 10 mils of 9.5 mil wide microstrip trace.
D- Test board vias, pads (footprint effects) for the QMS-DP connector side.
E- 10 mils of 9.5 mil wide microstrip trace.

The figure below shows the location of the measurement reference plane.



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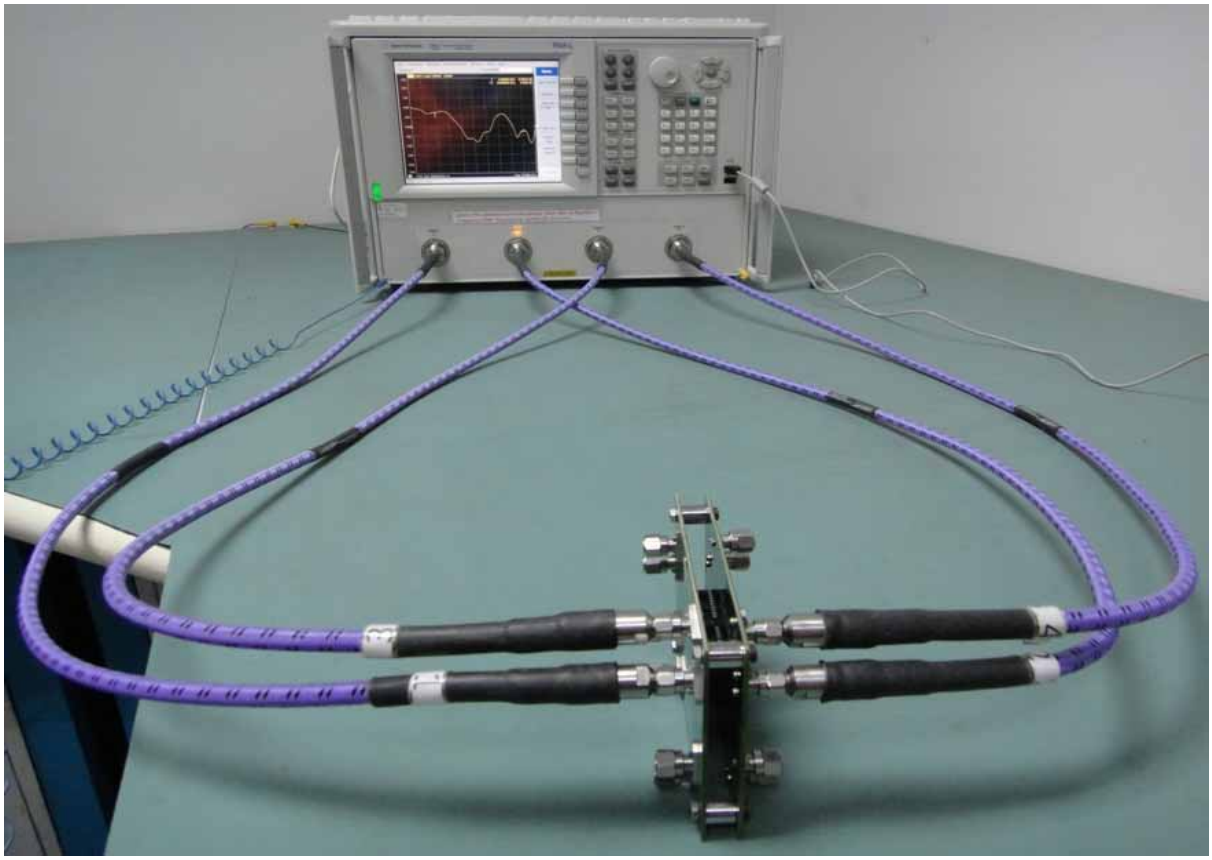
Appendix D – Test and Measurement Setup

The test instrument is the Agilent N5230C PNA-L network analyzer. Frequency domain data and graphs are obtained directly from the instrument. Post-processed time domain data and graphs are generated using convolution algorithms within Agilent ADS. The network analyzer is configured as follows:

Start Frequency – 300 KHz
Stop Frequency – 20 GHz
Number of points -1601
IFBW – 1 KHz

With these settings, the measurement time is approximately 20 seconds.

N5230C Measurement Setup



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Test Instruments

QTY	Description
1	Agilent N5230C PNA-L Network Analyzer (300 KHz to 20 GHz)
1	Agilent N4433A ecal module (300 KHz to 20 GHz)

Test Cables & Adapters

QTY	Description
4	Gore OWD01D02039-4 (DC-50 GHz)

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Appendix E - Frequency and Time Domain Measurements

Frequency (S-Parameter) Domain Procedures

The quality of any data taken with a network analyzer is directly related to the quality of the calibration standards and the use of proper test procedures. For this reason, extreme care is taken in the design of the LRM calibration standards, the SI test boards, and the selection of the PCB vendor.

The measurement process begins with a measurement of the LRM calibration standards. A coaxial SOLT calibration is performed using an N4433A ecal module. This measurement is required in order to obtain precise values of the line standard offset delay and frequency bandwidths. Measurements of the reflect and 2x through line standard can be used to determine the maximum frequency for which the calibration standards are valid. For the QFS-DP/ QMS-DP Series test boards, this is greater than 20 GHz.

From the LRM calibration standard measurements, a user defined calibration kit is developed and stored in the network analyzer. Calibration is then performed on all 4 ports following the calibration wizard within the Agilent N5230C. This calibration is saved and can be recalled at any time. Calibration takes roughly 30 minutes to perform.

Time Domain Procedures

Mathematically, Frequency Domain data can be transformed to obtain a Time Domain response. Perfect transformation requires Frequency Domain data from DC to infinity Hz. Fortunately, a very accurate Time Domain response can be obtained with bandwidth-limited data, such as measured with modern network analyzer.

The Time Domain responses were generated using Agilent ADS 2009 update 1. This tool has a transient convolution simulator, which can generate a Time Domain response directly from measured S-Parameters. An example of a similar methodology is provided in the Samtec Technical Note on domain transformation.
http://www.samtec.com/Technical_Library/reference/articles/pdfs/tech-note_using-PLTS-for-time-domain-data_web.pdf

Impedance (TDR)
A step pulse is applied to the touchstone model of the connector and the reflected voltage is monitored. The reflected voltage is converted to a reflection coefficient and then

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transformed into an impedance profile. All ports of the Touchstone model are terminated in 50 ohms.

Propagation Delay (TDT)
The Propagation Delay is a measure of the Time Domain delay through the connector and footprint. A step pulse is applied to the touchstone model of the connector and the transmitted voltage is monitored. The same pulse is also applied to a reference channel with zero loss, and the Time Domain pulses are plotted on the same graph. The difference in time, measured at the 50% point of the step voltage is the propagation delay.

Near-End Crosstalk (TDT) & Far End Crosstalk (TDT)
A step pulse is applied to the touchstone model of the connector and the coupled voltage is monitored. The amplitude of the peak-coupled voltage is recorded and reported as a percentage of the input pulse.

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Appendix F – Glossary of Terms

ADS – Advanced Design Systems
BC – Best Case crosstalk configuration
DUT – Device under test, term used for TDA IConnect & Propagation Delay waveforms
FD – Frequency domain
FEXT – Far-End Crosstalk
GSG – Ground–Signal-Ground; geometric configuration
GSSG - Ground–Signal-Signal-Ground; geometric configuration
HDV – High Density Vertical
NEXT – Near-End Crosstalk
OV – Optimal Vertical
OH – Optimal Horizontal
PCB – Printed Circuit Board
PPO – Pin Population Option
SE – Single-Ended
SI – Signal Integrity
SUT – System Under Test
S – Static (independent of PCB ground)
SOLT – acronym used to define Short, Open, Load & Thru Calibration Standards
TD – Time Domain
TDA – Time Domain Analysis
TDR – Time Domain Reflectometry
TDT – Time Domain Transmission
WC – Worst Case crosstalk configuration
Z – Impedance (expressed in ohms)